阅读申明

1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描叙上的差异，建议读者做出适当判断。
4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

Read Statement

ICZoom 拍明芯城

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.

2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader’s learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.

3. All product information provided on the website refer to solutions from manufacturers’ technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.

4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with “Datasheets”.

Downloaded from www.iczoom.com

PART INFORMATION	
Mfg Item Number	MPC860DEVR80D4
Mfg Item Name	PBGA 357 25*25*1.2P1.27

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-09-13
Response Document ID	5058K10790D049A1.47
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

MANUFACTURING	
Mfg Item Number	MPC860DEVR80D4
Mfg Item Name	PBGA 357 25*25*1.2P1.27
Version	ALL
Weight	2.096500
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

ICZoom 拍明芯城

Downloaded from www.iczoom.com

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
	6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c) : Copper alloy containing up to 4% lead by weight
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Downloaded from www.iczoom.com

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Die Encapsulant	0.76435						g				
Die Encapsulant		Metals	Aluminum, metal	7429-90-5		0.02361536	g	30896	3.0896	11264	1.1264
Die Encapsulant		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000076	g	1	0.0001	0	0
Die Encapsulant		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.00000076	g	1	0.0001	0	0
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.02361536	g	30896	3.0896	11264	1.1264
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00236184	g	3090	0.309	1126	0.1126
Die Encapsulant		Lead/Lead Compounds	Lead	7439-92-1		0.00000076	g	1	0.0001	0	0
Die Encapsulant		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00236184	g	3090	0.309	1126	0.1126
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.04329431	g	56642	5.6642	20650	2.065
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.66909901	g	875383	87.5383	319168	31.9168
Epoxy Die Attach	0.0066						g				
Epoxy Die Attach		Solvents, additives, and other materials	1,3,5-Triazine-2,4-diamine, 6-[2-(2-methyl-1H-imidazol-1-yl)ethyl]	38668-46-1		0.00005578	g	8451	0.8451	26	0.0026
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00085522	g	129579	12.9579	407	0.0407
Epoxy Die Attach		Plastics/polymers	4,4'-Dihydroxydiphenyl	92-88-6		0.00005578	g	8451	0.8451	26	0.0026
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00563322	g	853519	85.3519	2686	0.2686
Solder Balls - Lead Free	0.6053						g				
Solder Balls - Lead Free		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.00000424	g	7	0.0007	2	0.0002
Solder Balls - Lead Free		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000424	g	7	0.0007	2	0.0002
Solder Balls - Lead Free		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00000303	g	5	0.0005	1	0.0001
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.0042371	g	7000	0.7	2021	0.2021
Solder Balls - Lead Free		Metals	Iron, metal	7439-89-6		0.0000109	g	18	0.0018	5	0.0005
Solder Balls - Lead Free		Lead/Lead Compounds	Lead	7439-92-1		0.0000339	g	56	0.0056	16	0.0016
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.02275928	g	37600	3.76	10855	1.0855
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.57824731	g	955307	95.5307	275815	27.5815
Organic Substrate	0.6635						g				
Organic Substrate		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (26/74)	68891-46-3		0.00448924	g	6766	0.6766	2141	0.2141
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.04166183	g	62791	6.2791	19872	1.9872
Organic Substrate		Metals	Copper, metal	7440-50-8		0.12888753	g	194254	19.4254	61477	6.1477
Organic Substrate		Metals	Gold, metal	7440-57-5		0.00160036	g	2412	0.2412	763	0.0763
Organic Substrate		Solvents, additives, and other materials	Silicon	7440-21-3		0.00053876	g	812	0.0812	256	0.0256
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.00681149	g	10266	1.0266	3248	0.3248
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3		0.1962361	g	295759	29.5759	93601	9.3601
Organic Substrate		Plastics/polymers	Other acrylic resins	-		0.05279602	g	79572	7.9572	25182	2.5182
Organic Substrate		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.23047867	g	347368	34.7368	109934	10.9934
Bonding Wire, PdCu	0.0143						g				
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.0140283	g	981000	98.1	6691	0.6691
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000143	g	1000	0.1	6	0.0006
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.0002574	g	18000	1.8	122	0.0122
Silicon Semiconductor Die	0.04245						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000849	g	20000	2	404	0.0404
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.041601	g	980000	98	19843	1.9843

Downloaded from www.iczoom.com

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

Downloaded from www.iczoom.com